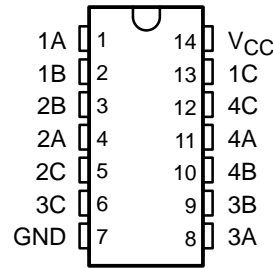


SN74HC4066 QUADRUPLE BILATERAL ANALOG SWITCH

SCLS325G – MARCH 1996 – REVISED JULY 2003

- Wide Operating Voltage Range of 2 V to 6 V
- Typical Switch Enable Time of 18 ns
- Low Power Consumption, 20- μ A Max I_{CC}
- Low Input Current of 1 μ A Max
- High Degree of Linearity
- High On-Off Output-Voltage Ratio
- Low Crosstalk Between Switches
- Low On-State Impedance . . .
50- Ω TYP at $V_{CC} = 6$ V
- Individual Switch Controls

D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



description/ordering information

The SN74HC4066 is a silicon-gate CMOS quadruple analog switch designed to handle both analog and digital signals. Each switch permits signals with amplitudes of up to 6 V (peak) to be transmitted in either direction.

Each switch section has its own enable input control (C). A high-level voltage applied to C turns on the associated switch section.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 25	SN74HC4066N	SN74HC4066N
	SOIC – D	Tube of 50	SN74HC4066D	HC4066
		Reel of 2500	SN74HC4066DR	
		Reel of 250	SN74HC4066DT	
	SOP – NS	Reel of 2000	SN74HC4066NSR	HC4066
	SSOP – DB	Reel of 2000	SN74HC4066DBR	HC4066
	TSSOP – PW	Tube of 90	SN74HC4066PW	HC4066
		Reel of 2000	SN74HC4066PWR	
		Reel of 250	SN74HC4066PWT	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each switch)

INPUT CONTROL (C)	SWITCH
L	OFF
H	ON



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

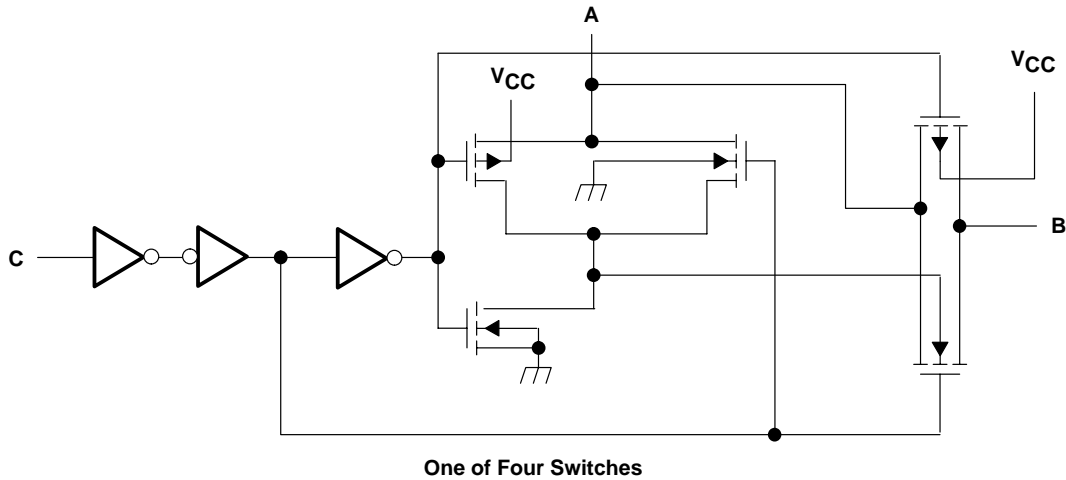
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2003, Texas Instruments Incorporated

SN74HC4066 QUADRUPLE BILATERAL ANALOG SWITCH

SCLS325G – MARCH 1996 – REVISED JULY 2003

logic diagram, each switch (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1)	-0.5 V to 7 V
Control-input diode current, I_I ($V_I < 0$ or $V_I > V_{CC}$)	± 20 mA
I/O port diode current, I_I ($V_I < 0$ or $V_{I/O} > V_{CC}$)	± 20 mA
On-state switch current ($V_{I/O} = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND	± 50 mA
Package thermal impedance, θ_{JA} (see Note 2):		
D package	86°C/W
DB package	96°C/W
N package	80°C/W
NS package	76°C/W
PW package	113°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to ground unless otherwise specified.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

SN74HC4066 QUADRUPLE BILATERAL ANALOG SWITCH

SCLS325G – MARCH 1996 – REVISED JULY 2003

recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	2†	5	6	V
V _{I/O}	I/O port voltage	0		V _{CC}	V
V _{IH}	High-level input voltage, control inputs	V _{CC} = 2 V	1.5	V _{CC}	V
		V _{CC} = 4.5 V	3.15	V _{CC}	
		V _{CC} = 6 V	4.2	V _{CC}	
V _{IL}	Low-level input voltage, control inputs	V _{CC} = 2 V	0	0.3	V
		V _{CC} = 4.5 V	0	0.9	
		V _{CC} = 6 V	0	1.2	
Δt/Δv	Input transition rise/fall time	V _{CC} = 2 V		1000	ns
		V _{CC} = 4.5 V		500	
		V _{CC} = 6 V		400	
T _A	Operating free-air temperature	-40		85	°C

† With supply voltages at or near 2 V, the analog switch on-state resistance becomes very nonlinear. It is recommended that only digital signals be transmitted at these low supply voltages.

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
r _{on}	On-state switch resistance I _T = -1 mA, V _I = 0 to V _{CC} , V _C = V _{IH} (see Figure 1)	2 V		150			Ω	
		4.5 V		50	85	106		
		6 V		30				
r _{on(p)}	Peak on-state resistance V _I = V _{CC} or GND, V _C = V _{IH} , I _T = -1 mA	2 V		320			Ω	
		4.5 V		70	170	215		
		6 V		50				
I _I	Control input current	V _C = 0 or V _{CC}	6 V	±0.1	±100	±1000	nA	
I _{soff}	Off-state switch leakage current	V _I = V _{CC} or 0, V _O = V _{CC} or 0, V _C = V _{IL} (see Figure 2)	6 V		±0.1	±5	μA	
I _{son}	On-state switch leakage current	V _I = V _{CC} or 0, V _C = V _{IH} (see Figure 3)	6 V		±0.1	±5	μA	
I _{CC}	Supply current	V _I = 0 or V _{CC} , I _O = 0	6 V		2	20	μA	
C _i	Input capacitance	A or B	5 V	9			pF	
		C		3	10	10		
C _f	Feed-through capacitance	A to B		0.5			pF	
C _O	Output capacitance	A or B	5 V	9			pF	



SN74HC4066

QUADRUPLE BILATERAL ANALOG SWITCH

SCLS325G – MARCH 1996 – REVISED JULY 2003

switching characteristics over recommended operating free-air temperature range

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V _{CC}	T _A = 25°C			MIN	MAX	UNIT
					MIN	TYP	MAX			
t _{PLH} , t _{PHL} Propagation delay time	A or B	B or A	C _L = 50 pF (see Figure 4)	2 V		10	60		75	ns
				4.5 V		4	12		15	
				6 V		3	10		13	
t _{PZH} , t _{PZL} Switch turn-on time	C	A or B	R _L = 1 kΩ, C _L = 50 pF (see Figure 5)	2 V		70	180		225	ns
				4.5 V		21	36		45	
				6 V		18	31		38	
t _{PLZ} , t _{PHZ} Switch turn-off time	C	A or B	R _L = 1 kΩ, C _L = 50 pF (see Figure 5)	2 V		50	200		250	ns
				4.5 V		25	40		50	
				6 V		22	34		43	
f _I Control input frequency	C	A or B	C _L = 15 pF, R _L = 1 kΩ, V _C = V _{CC} or GND, V _O = V _{CC} /2 (see Figure 6)	2 V		15				MHz
				4.5 V		30				
				6 V		30				
Control feed-through noise	C	A or B	C _L = 50 pF, R _{in} = R _L = 600 Ω, V _C = V _{CC} or GND, f _{in} = 1 MHz (see Figure 7)	4.5 V		15				mV (rms)
				6 V		20				

operating characteristics, V_{CC} = 4.5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance per gate	C _L = 50 pF, f = 1 MHz	45	pF
Minimum through bandwidth, A to B or B to A [†] [20 log (V _O /V _I)] = -3 dB	C _L = 50 pF, V _C = V _{CC} , R _L = 600 Ω, (see Figure 8)	30	MHz
Crosstalk between any switches [‡]	C _L = 10 pF, f _{in} = 1 MHz, R _L = 50 Ω, (see Figure 9)	45	dB
Feed through, switch off, A to B or B to A [‡]	C _L = 50 pF, f _{in} = 1 MHz, R _L = 600 Ω, (see Figure 10)	42	dB
Amplitude distortion rate, A to B or B to A	C _L = 50 pF, f _{in} = 1 kHz, R _L = 10 kΩ, (see Figure 11)	0.05%	

[†] Adjust the input amplitude for output = 0 dBm at f = 1 MHz. Input signal must be a sine wave.

[‡] Adjust the input amplitude for input = 0 dBm at f = 1 MHz. Input signal must be a sine wave.



PARAMETER MEASUREMENT INFORMATION

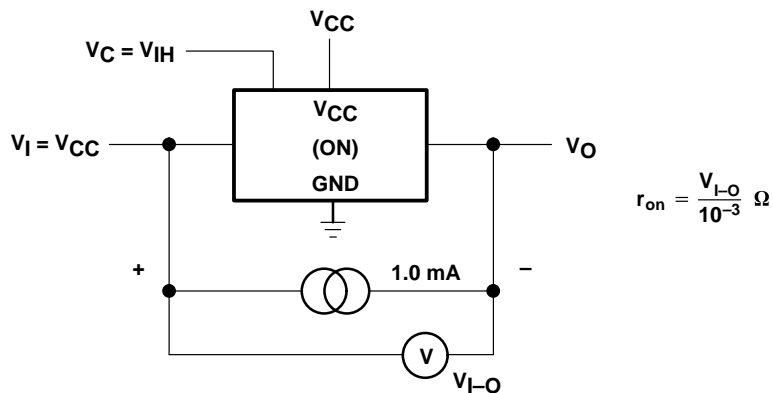


Figure 1. On-State Resistance Test Circuit

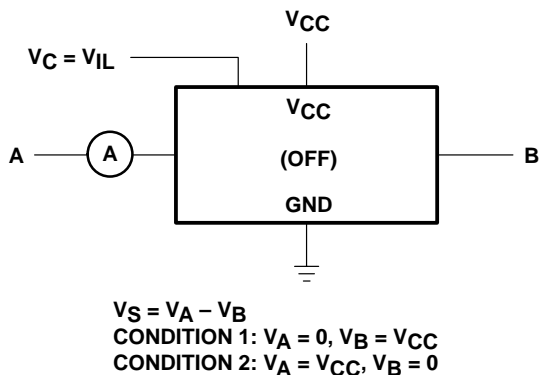


Figure 2. Off-State Switch Leakage-Current Test Circuit

SN74HC4066 QUADRUPLE BILATERAL ANALOG SWITCH

SCLS325G – MARCH 1996 – REVISED JULY 2003

PARAMETER MEASUREMENT INFORMATION

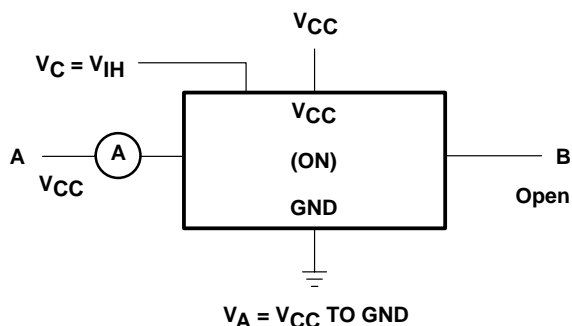


Figure 3. On-State Leakage-Current Test Circuit

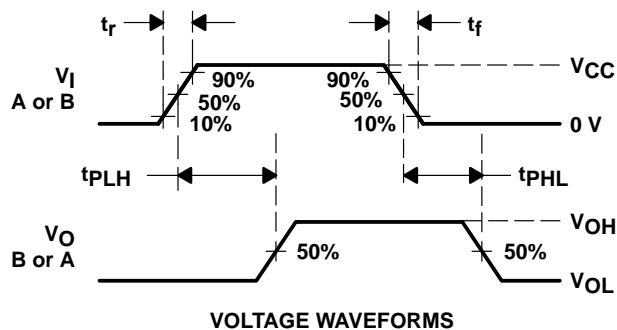
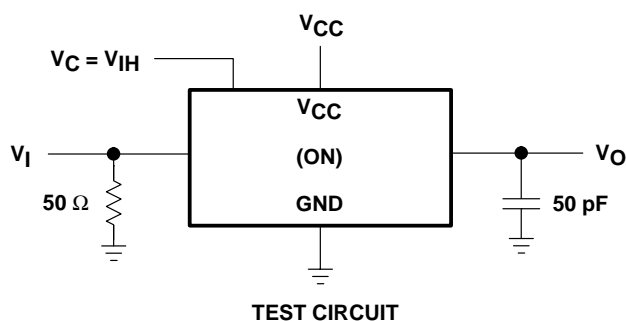
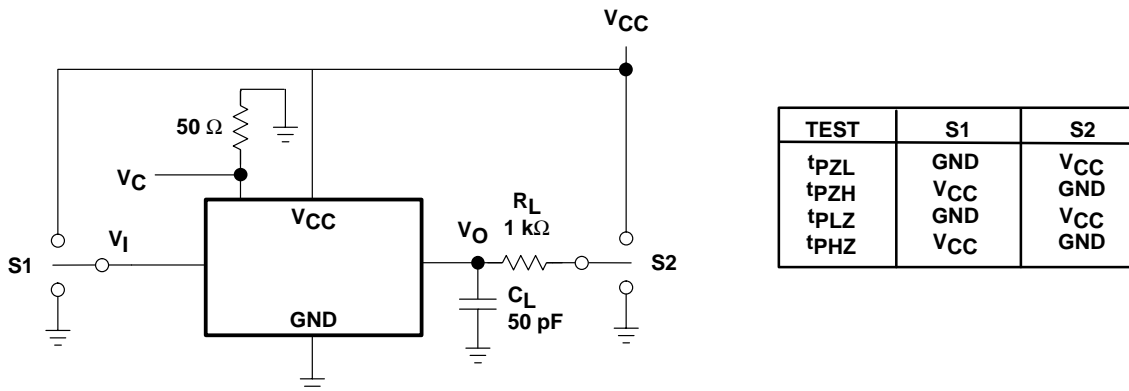


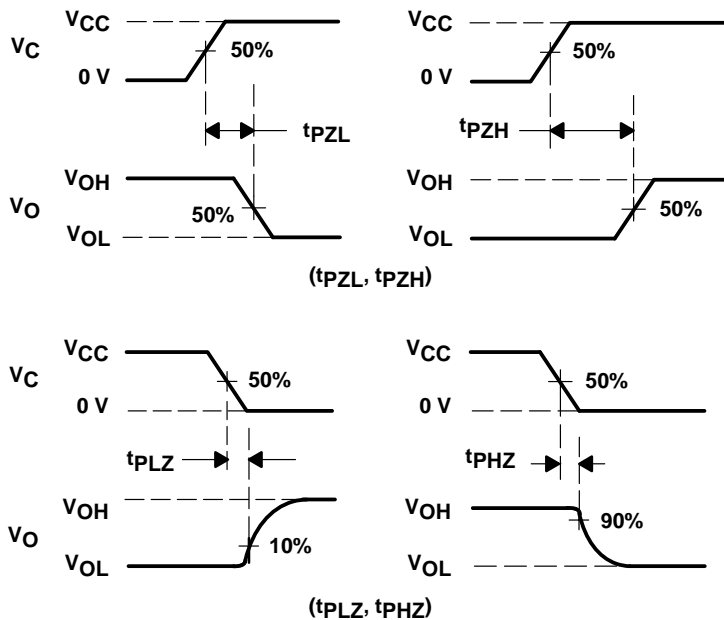
Figure 4. Propagation Delay Time, Signal Input to Signal Output

PARAMETER MEASUREMENT INFORMATION



TEST	S1	S2
t_{PZL}	GND	V_{CC}
t_{PZH}	V_{CC}	GND
t_{PLZ}	GND	V_{CC}
t_{PHZ}	V_{CC}	GND

TEST CIRCUIT



VOLTAGE WAVEFORMS

Figure 5. Switching Time (t_{PZL} , t_{PLZ} , t_{PZH} , t_{PHZ}), Control to Signal Output

SN74HC4066 QUADRUPLE BILATERAL ANALOG SWITCH

SCLS325G – MARCH 1996 – REVISED JULY 2003

PARAMETER MEASUREMENT INFORMATION

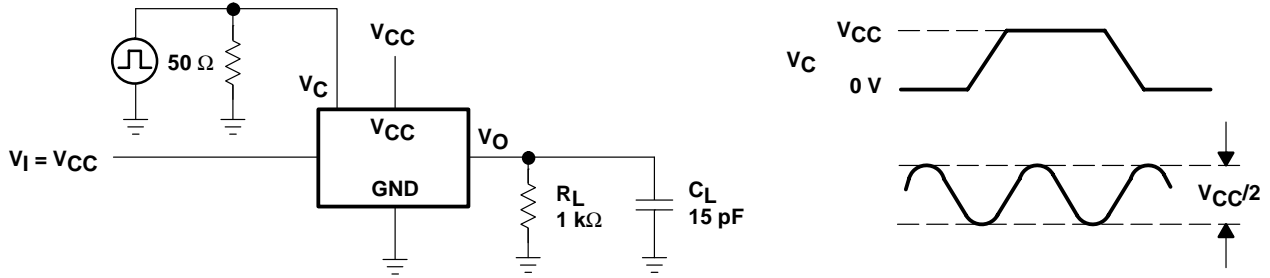


Figure 6. Control-Input Frequency

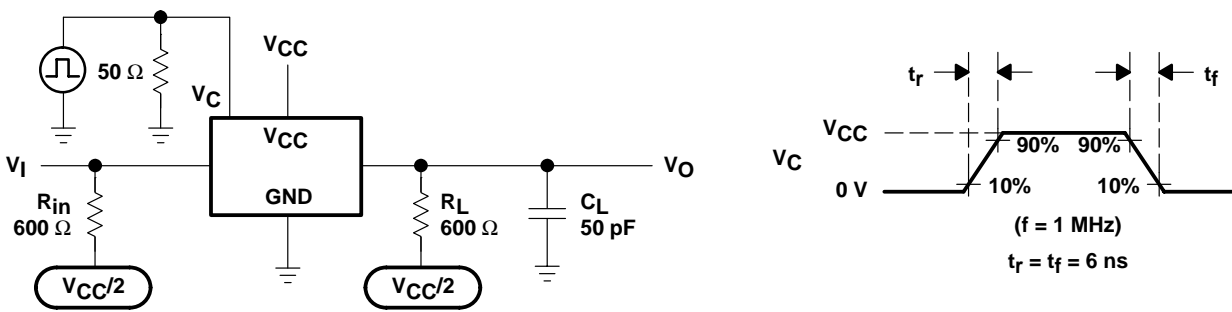


Figure 7. Control Feed-Through Noise

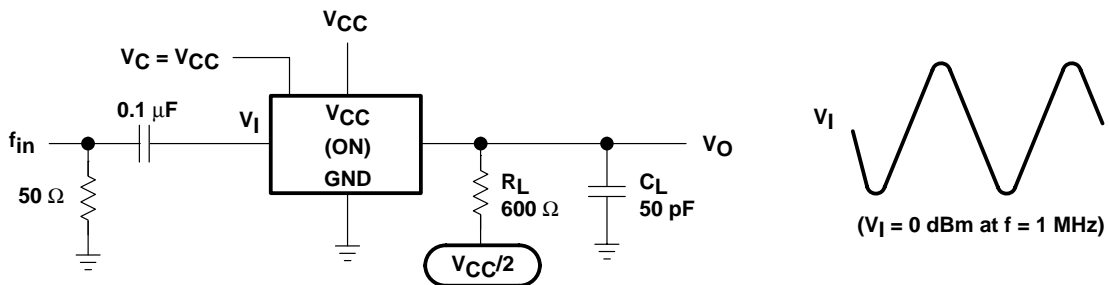


Figure 8. Minimum Through Bandwidth

PARAMETER MEASUREMENT INFORMATION

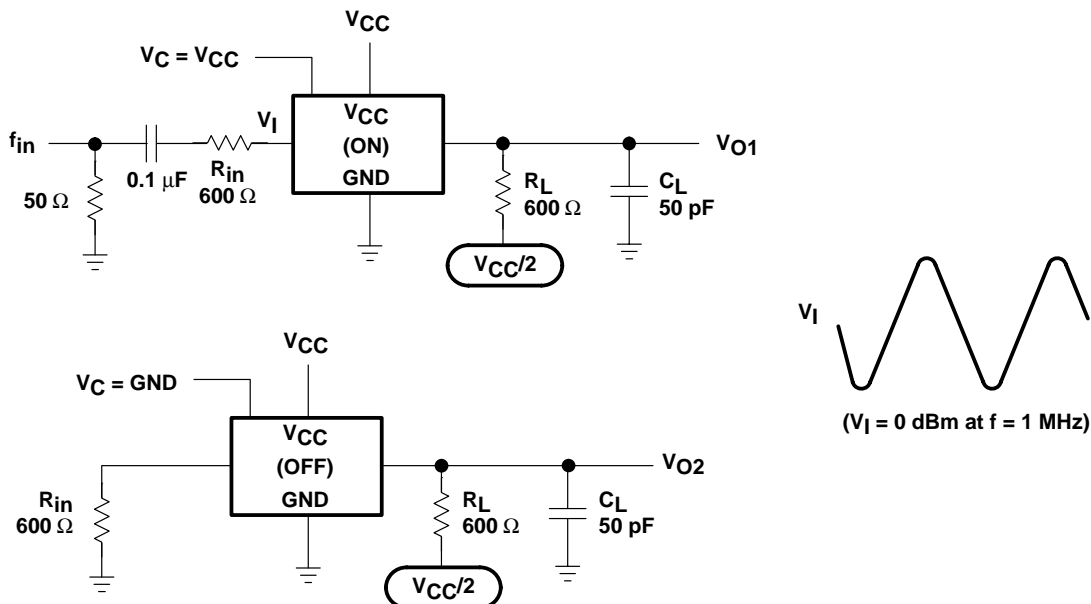


Figure 9. Crosstalk Between Any Two Switches

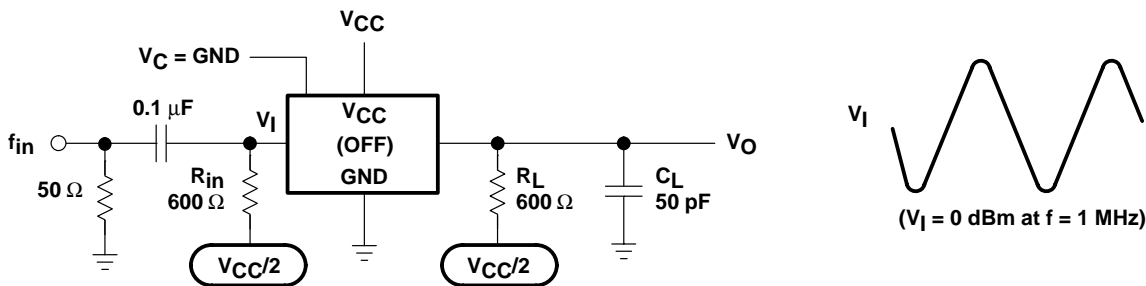


Figure 10. Feed Through, Switch Off

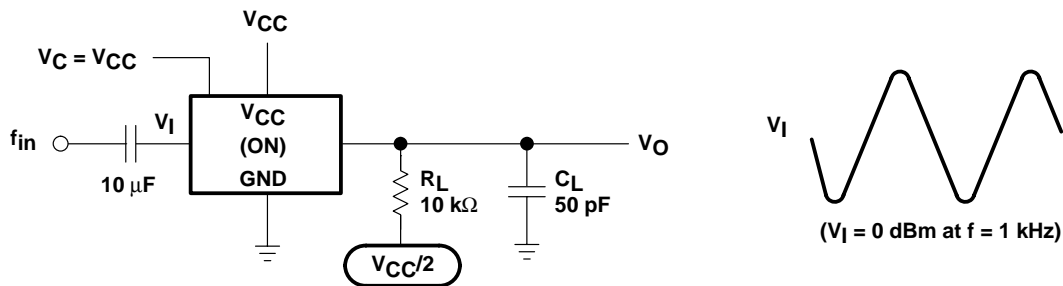


Figure 11. Amplitude-Distortion Rate

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2007, Texas Instruments Incorporated

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74HC4066D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74HC4066DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066DT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066DTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066DTG4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC4066NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC4066NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74HC4066PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066PWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066PWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
SN74HC4066PWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

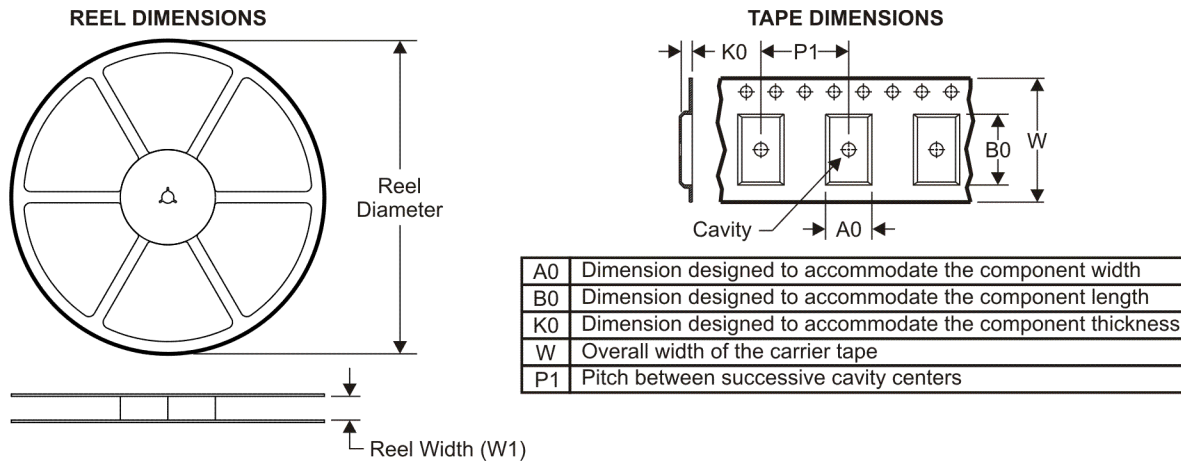
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC4066DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74HC4066DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC4066NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC4066PWR	TSSOP	PW	14	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC4066DBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74HC4066DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74HC4066NSR	SO	NS	14	2000	346.0	346.0	33.0
SN74HC4066PWR	TSSOP	PW	14	2000	346.0	346.0	29.0

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

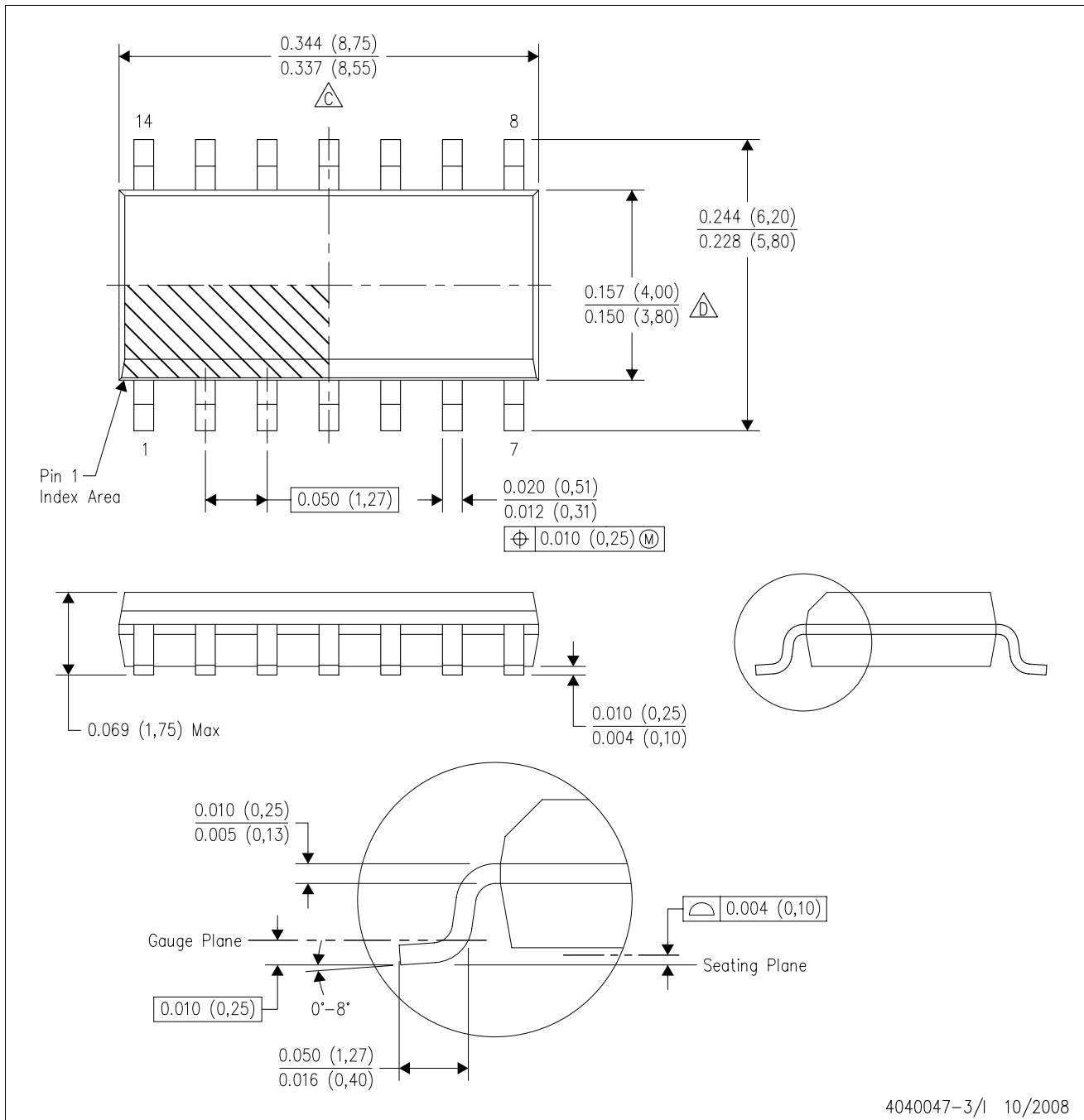
14-PINS SHOWN





- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 -  Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2008, Texas Instruments Incorporated